DOCUMENT TYPE: PLP

DOCUMENT ID #: 90-100103

REVISION: C-000

DOCUMENT TITLE: PACKAGE LAND PATTERN, [T203A3Y] TQFN

EFFECTIVE DATE: 01/30/2024

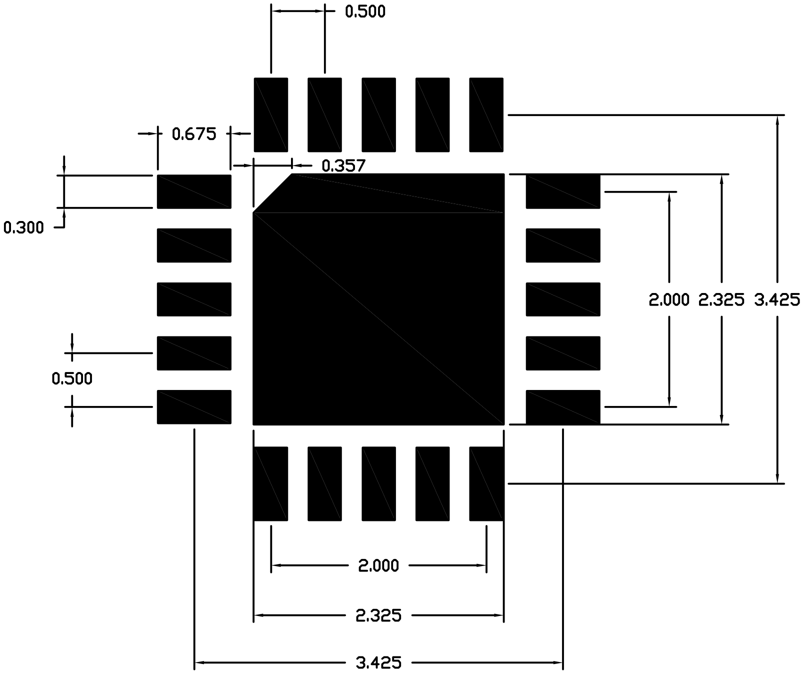
EXPIRATION DATE:

CHANGE NUMBER: 1203434

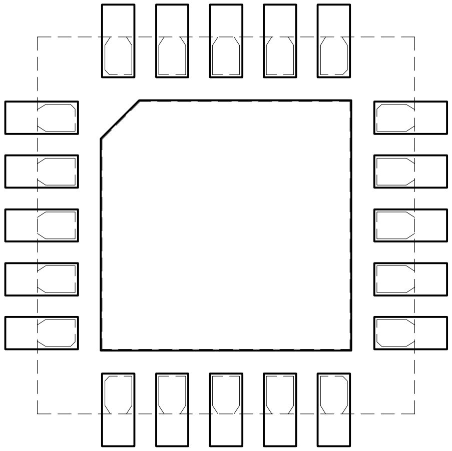
ORIGINATOR: Aurelio Giron Jr.

REASON FOR CHANGE:
Adding new package code T203A3Y+2C

RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



PKG. CODES
[T203A3Y+1C]
[T203A3Y+2C]
[T203A3YMK+1]

NOTES:
1. REFERENCE PKG. OUTLINE: 21-100306, 21-100468
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. TOLERANCE: +/- 0.02 MM.
4. ALL DIMENSIONS APPLY TO LEADED, PbFREE PACKAGES.
5. ALL DIMENSIONS IN MM.

-DRAWING NOT TO SCALE-

This document (including dimensions, notes & specs) is a recommendaton based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Analog Devices Inc. (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice.
Contact technical support at https://www.analog.com/en/support for further questions.

ANALOG
DEVICES

TITLE:
PACKAGE LAND PATTERN,
[T203A3Y] TQFN

APPROVAL: CHUCK XIA
DOCUMENT CONTROL NO.: 90-100103
REV.: C
1/1

REVISION HISTORY

REV	CHANGES MADE	DATE	INIT.
A	CN 1034214. INITIAL RELEASE	05/05/18	BG
B	CN 1076971. Add pkgcode T203A3YMK-1, pod 21-100468. Enlarge pad for EP to 2.325x2.325 to cover EP area. Update Title.	2/03/20	BG
C	CN 1203434 Adding new package code T203A3Y+2C	01/30/24	AG

TITLE: PACKAGE LAND PATTERN, [T203A3Y] TQFN

DOCUMENT I.D.	REVISION	PAGE
90-100103	C	2

ANALOG DEVICES